

September 2010

FSAV330 — 4-Channel, 2:1 Video Switch

Features

- Replacement for the P15V330
- Wide Bandwidth: 300MHz
- 4Ω Switch Connection between Two Ports
- Minimal Propagation Delay through the Switch
- Low Icc
- Zero Bounce in Flow-through Mode
- Control Inputs Compatible with TTL Level

Applications

- Set-Top Boxes
- Flat Panel Displays
- CRT Displays
- DVD RW

Description

The FSAV330 video switch is a quad, single-pole / double-throw, high-speed CMOS TTL-compatible video switch. The low on resistance of the switch allows inputs to be connected to outputs without adding propagation delay or generating additional ground bounce noise.

When /OE is LOW, the select pin connects the A port to the selected B port output. When /OE is HIGH, the switch is OPEN and a high-impedance state exists between the two ports.

Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method
FSAV330MX	-40 to +85°C	16-Lead, Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150 inch Narrow	Tape and Reel
FSAV330MTCX	-40 to +85°C	16-, Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide	Tape and Reel
FSAV330QSCX	-40 to +85°C	16-Lead, Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150 inch Wide	Tape and Reel

The Fairchild switch family derives from and embodies Fairchild's proven switch technology used for several years in its 74LVX3L384 (FST3384) bus switch product.

Pin Configurations

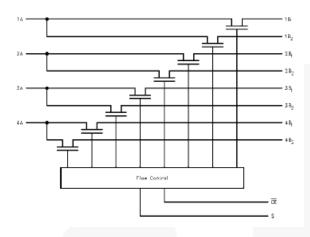


Figure 1. Logic Diagram

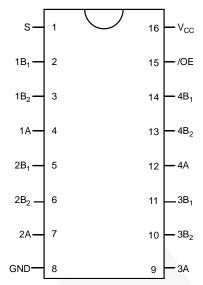


Figure 2. Pin Assignments

Pin Descriptions

Pin #	Name	Description
15	/OE	Bus Switch Enabled
1	S	Select Input
4,7,9,12	Α	Bus A
2,3,5,6,10,11,13,14	B ₁ -B ₂	Bus B
8	GND	Ground
16	V _{cc}	Supply Voltage

Truth Table

S	/OE	Function
Don't Care	HIGH	Disconnected
LOW	LOW	A=B ₁
HIGH	LOW	A=B ₂

Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V _{cc}	Supply Voltage	-0.5	+7.0	V
Vs	DC Switch Voltage	-0.5	+7.0	V
V _{IN}	DC Input Voltage ⁽¹⁾	-0.5	+7.0	V
I _{IK}	DC Input Diode Current	-50		mA
I _{OUT}	DC Output Sink Current		128	mA
I_{CC}/I_{GND}	DC V _{CC} / GND Current		±100	mA
T _{STG}	Storage Temperature Range	-65	+150	°C
ESD	Human Body Model, JESD22-A114		4000	V

Note

Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter		Min.	Max.	Unit
V _{CC}	Power Supply		4.0	5.5	V
V _{IN}	Input Voltage	0	5.5	V	
V _{OUT}	Output Voltage		0	5.5	V
	Input Dies and Fall Time	Switch Control Input	0	5	ns/V
t_r, t_f	Input Rise and Fall Time Switch I/O		0	DC	115/ V
T _A	Operating Temperature, Free Air		-40	+85	°C

Note:

2. Unused control inputs must be held HIGH or LOW; they may not float.

^{1.} The input and output negative voltage ratings may be exceeded if the input and output diode current ratings are observed.

DC Electrical Characteristics

Typical values are at V_{CC} =5.0V and T_A = +25°C. Minimum and maximum values are at T_A = -40 to +85°C.

Symbol	Parameter	Conditions	V _{cc} (V)	Min.	Тур.	Max.	Units
V _{ANALOG}	Analog Signal Range		5.0	0		2	V
V_{IK}	Clamp Diode Voltage	I _{IN} =-18mA	4.5			-1.2	V
V_{IH}	High-Level Input Voltage		4.0 to 5.5	2.0			V
V_{IL}	Low-Level Input Voltage		4.0 to 5.5			0.8	V
I_1	Input Leakage Current	$0 \le V_{IN} \le 5.5V$	5.5			±1.0	μA
loz	Off-State Leakage Current	$0 \le A, B \le V_{CC}$	5.5			±1.0	μA
D	Switch On Resistance ⁽³⁾	V_{IN} =1.0V, R_I =75 Ω , I_{ON} =13mA	4.5		3	7	0
R _{ON}	Switch On Resistance	V_{IN} =2.0V, R_I =75 Ω , I_{ON} =26mA	4.5		7	10	Ω
Icc	Quiescent Supply Current	V _{IN} =V _{CC} or GND, I _{OUT} =0	5.5			3	μΑ
Δl _{CC}	Increase in I _{CC} per Input	One Input at 3.4V Other Inputs at V _{CC} or GND	5.5			2.5	mA

Note:

3. Measured by the voltage drop between the A and B pins at the indicated current through the switch. On resistance is determined by the lower of the voltages on the A or B pins.

AC Electrical Characteristics

 T_A =-40 to +85°C, C_L =50pF, R_U = R_D =500 Ω .

Symbol	Parameter	Conditions	$V_{CC} = 4.5 - 5.5V$		V _{CC} =4.0V		Units	Figure	
Syllibol	Farameter	Conditions	Min.	Тур.	Max.	Min.	Max.	Ullits	rigure
	Output Enable Time, Select to Bus B	V _I =7V for t _{PZL}			5.2		5.7	20	Figure 3
t _{PZH} , t _{PZL}	Output Enable Time, /OE to Bus A, B	V _I =Open for t _{PZH}			5.1		5.6	ns	Figure 4
	Output Disable Time, Select to Bus B	\/_7\/ for t			5.2		5.5		Figure 2
t _{PHZ} , t _{PLZ}	Output Disable Time, Output Enable Time /OE to Bus A, B	V _I =7V for t _{PLZ} V _I =Open for t _{PHZ}			5.5		5.5	ns	Figure 3 Figure 4
B _W	-3dB Bandwidth ⁽⁴⁾	R _L =150Ω, T _A =25°C	300					MHz	
X _{TALK}	Crosstalk	R_{IN} =10 Ω , R_L =150 Ω , f=10MHz		-58				dB	
D_G	Differential Gain	R _L =150Ω, f=3.58MHz		0.64				%	
D _P	Differential Phase	R _L =150Ω, f=3.58MHz		0.1				0	
O _{IRR}	Off Isolation	R _L =150Ω, f=10MHz		-60				dB	

Note:

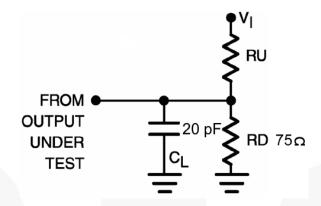
4. This parameter is guaranteed by device characterization, not production tested.

Capacitance

T_A=+25°C, f=1MHz. Capacitance is characterized, not production tested.

Symbol Parameter		Parameter	Conditions	Тур.	Units
C _{IN} Control Pin Input Capacitance		Control Pin Input Capacitance	V _{CC} =5.0V	3	pF
	A Port		V (05 5 0V)	7	1
C _{I/O}	B Port	Input / Output Capacitance	V _{CC} , /OE=5.0V	5	pF
	C _{ON}	Switch On Capacitance	V _{CC} =5.0V, /OE=0V	12	pF

AC Loadings and Waveforms



Notes:

- Input drive by 50Ω source terminated in 50Ω . C_L includes load and stray capacitance. Input PRR=1.0MHz, t_W =500ns.

Figure 3. AC Test Circuit

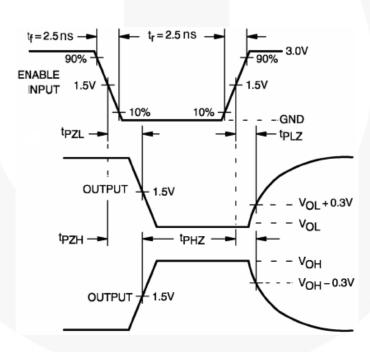


Figure 4. AC Waveforms

Physical Dimensions

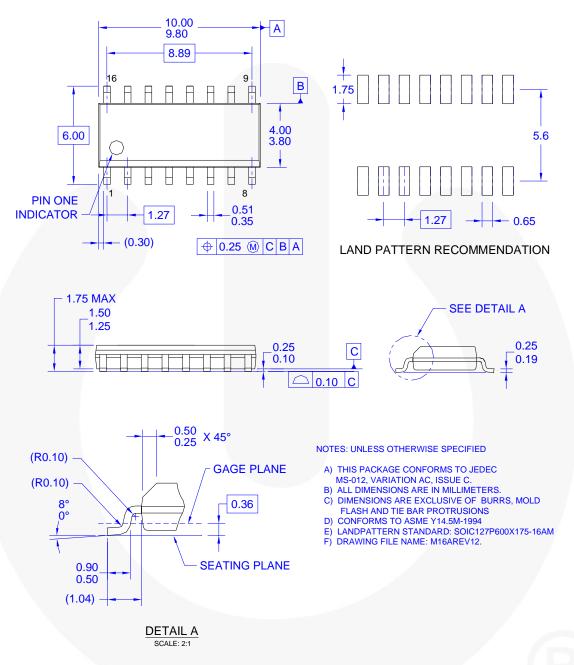


Figure 5. 16-Lead, Small Outline Integrated Circuit (SOIC), JEDEC MS-012, 0.150-inch Narrow

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○ 0.10 M A-B [.197](3.7)[.280] [.146] 3.9 [.154] [.236] (0.635) 0.10 M A-B (0.317)[.025] [.013] ○ 0.20 M C 0.635 2X N/2 TIPS [.025] 0.27 LAND PATTERN [.011] **TOP VIEW** RECOMMENDATION 1.357±0.127 DETAIL A ○ 0.10 M C 16 X [.053±0.005] -10°±5 0.010 1.6±0.05 [.063±0.002] **END VIEW** SIDE VIEW 0.5 ×45° [.02 ×45°] R0.09 Min-GAGE NOTES : .254 PLANE $4^{\circ} + 4^{\circ}$ [0.010] A. THIS PACKAGE CONFORMS TO JEDEC MO-137 VARIATION AB B. PRIMARY DIMENSIONS IN MILLIMETERS SEATING REFERENCE DIMENSIONS IN INCHES [0.020-0.0295] C. DRAWING CONFORMS TO PLANE ASME Y14.5M-1994 D. DIMENSIONS ARE EXCLUSIVE OF BURRS, [0.039] **DETAIL A** MOLD FLASH, AND TIE BAR EXTRUSIONS.

Figure 6. 16-Lead, Quarter Size Outline Package (QSOP), JEDEC MO-137, 0.150-inch Wide

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MQA16AREVB

Physical Dimensions

Physical Dimensions 5.00±0.10 4.55 5.90 4.45 7.35 В 6.4 0.65 4.4 ± 0.1 1.45 3.2 ALL LEAD TIPS 5.00 PIN #1 IDENT. LAND PATTERN RECOMMENDATION (F) 0.11 SEE DETAIL A ALL LEAD TIPS 1.1 MAX (0.90)○ 0.1 C 0.09-0.20 -C-0.10±0.05 0.65 0.19 - 0.30TOP AND BOTTOM ⊕ 0.10M A BS CS **GAGE PLANE** NOTES: 0.25 0°-8° A. CONFORMS TO JEDEC REGISTRATION MO-153, VARIATION AB, **B. DIMENSIONS ARE IN MILLIMETERS** C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH, AND TIE BAR EXTRUSIONS 0.6±0.1 SEATING PLANE D. DIMENSIONING AND TOLERANCES PER ANSI Y14.5M, 1994 E. DRAWING FILE NAME: MTC16REV4 **DETAIL** A F. LAND PATTERN RECOMMENDATION PER IPC7351 - ID# TSOP65P640X110-16N

MTC16rev4

Figure 7. 16-Lead, Thin Shrink Small Outline Package (TSSOP), JEDEC MO-153, 4.4mm Wide

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